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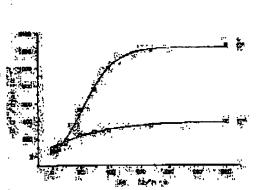
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(54) PHOTOSENSITIVE RESIN COMPOSITION

(57)Abstract

PROBLEM TO BE SOLVED: To obtain a photosensitive resin compsn. using a relatively small amt, of Fullerene and curable with visible light. SOLUTION: This photosensitive resin compsn. contains Fullerene and a high molecular compd, having a functional group capable of reacting with the Fullerene under irradiation with visible light. A negative type image element is formed as follows; a layer of this compsn. is formed and irradiated with visible light through a photomask having a visible radiation transmitting pattern, the irradiated part in the layer is cured and the uncured part in the layer is removed to form a patterned resist film. A device is produced by etching an image forming layer through the resist film and then removing the resist film.



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